1. General description

Planar passivated Silicon Controlled Rectifier with ultra-sensitive gate in a SOT54 (TO-92) plastic package.

2. Features and benefits

- · High voltage capability
- · Planar passivated for voltage ruggedness and reliability
- Ultra sensitive gate

3. Applications

- Electronic ballasts
- · Safety shut down and protection circuits
- Sensing circuits
- · Smoke detectors
- Switched Mode Power Supplies

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{RRM}	repetitive peak reverse voltage		-	-	600	V
I _{T(AV)}	average on-state current	half sine wave; T _{lead} ≤ 67 °C; <u>Fig. 1</u>	-	-	0.51	Α
I _{T(RMS)}	RMS on-state current	half sine wave; T _{lead} ≤ 67 °C; <u>Fig. 2</u> ; <u>Fig. 3</u>	-	-	0.8	Α
I _{TSM}	non-repetitive peak on- state current	half sine wave; $T_{j(init)}$ = 25 °C; t_p = 10 ms; Fig. 4; Fig. 5	-	-	8	Α
		half sine wave; $T_{j(init)}$ = 25 °C; t_p = 8.3 ms	-	-	9	Α
T _j	junction temperature		-	-	125	°C
Static characte	eristics					
I _{GT}	gate trigger current	$V_D = 12 \text{ V}; I_T = 10 \text{ mA}; T_j = 25 \text{ °C};$ Fig. 7	0.5	-	7	μA
Dynamic chara	acteristics					
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 402 V; T_j = 125 °C; R_{GK} = 1 kΩ; (V_{DM} = 67% of V_{DRM}); exponential waveform; Fig. 13; Fig. 14	75	-	-	V/µs

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5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	Α	anode		А - [-] - К
2	G	gate		Ġ sym037
3	K	cathode	TO-92 (SOT54)	Symos

6. Ordering information

Table 3. Ordering information

	•					
Type number		Package		Version		
		Name	Description	Version		
	N0118GA	TO-92	plastic single-ended leaded (through hole) package; 3 leads	SOT54		

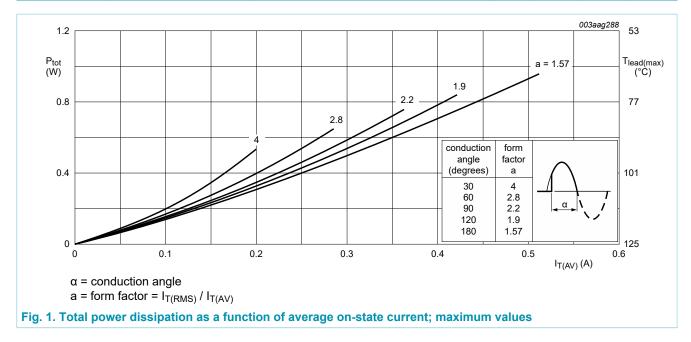
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7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	600	V
V_{RRM}	repetitive peak reverse voltage		-	600	V
I _{T(AV)}	average on-state current	half sine wave; T _{lead} ≤ 67 °C; <u>Fig. 1</u>	-	0.51	Α
I _{T(RMS)}	RMS on-state current	half sine wave; T _{lead} ≤ 67 °C; <u>Fig. 2</u> ; <u>Fig. 3</u>	-	0.8	Α
I _{TSM}	non-repetitive peak on- state current	half sine wave; $T_{j(init)}$ = 25 °C; t_p = 10 ms; Fig. 4; Fig. 5	-	8	А
		half sine wave; T _{j(init)} = 25 °C; t _p = 8.3 ms	-	9	Α
I ² t	I ² t for fusing	t_p = 10 ms; SIN	-	0.32	A²s
dl _T /dt	rate of rise of on-state current	$I_T = 0.8 \text{ A}$; $I_G = 10 \text{ mA}$; $dI_G/dt = 0.1 \text{ A/}\mu\text{s}$	-	50	A/µs
I _{GM}	peak gate current		-	1	Α
V_{RGM}	peak reverse gate voltage		-	5	V
P _{GM}	peak gate power		-	2	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	0.1	W
T _{stg}	storage temperature		-40	150	°C
T _j	junction temperature		-	125	°C



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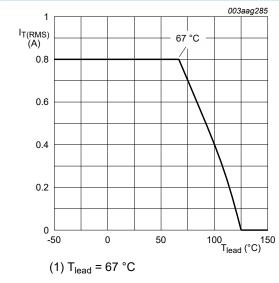


Fig. 2. RMS on-state current as a function of lead temperature; maximum values

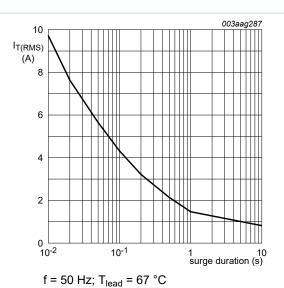


Fig. 3. RMS on-state current as a function of surge duration; maximum values

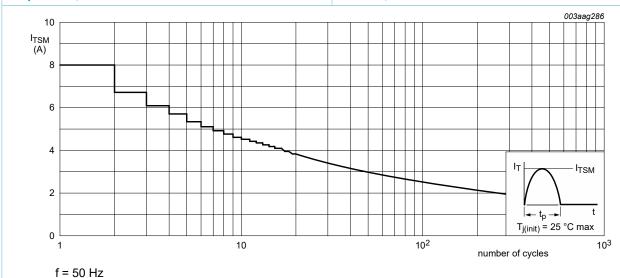
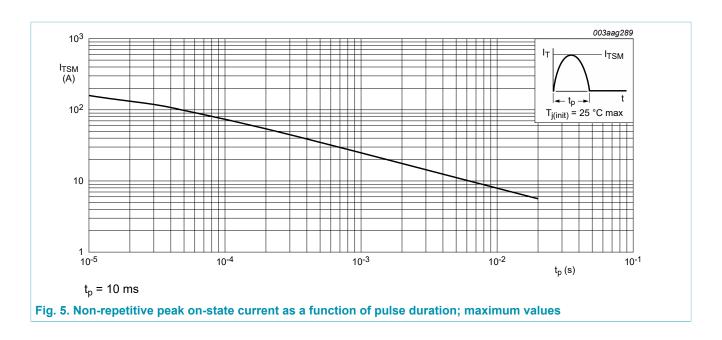


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

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8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-lead)}	thermal resistance from junction to lead	<u>Fig. 6</u>	-	-	60	K/W
R _{th(j-a)}	thermal resistance from junction to ambient free air	printed circuit board mounted: lead length = 4 mm	-	150	-	K/W

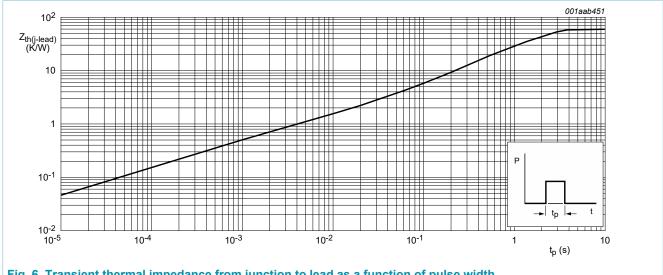


Fig. 6. Transient thermal impedance from junction to lead as a function of pulse width

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9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static chara	acteristics					
I _{GT}	gate trigger current	$V_D = 12 \text{ V}; I_T = 10 \text{ mA}; T_j = 25 \text{ °C};$ Fig. 7	0.5	-	7	μΑ
IL	latching current	$V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; T_j = 25 ^{\circ}\text{C}; Fig. 8$	-	-	6	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 9</u> ; <u>Fig. 10</u>	-	-	5	mA
V_T	on-state voltage	I _T = 1.6 A; T _j = 25 °C; <u>Fig. 11</u>	-	1.4	1.95	V
V_{GT}	gate trigger voltage	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C};$ Fig. 12	-	-	0.8	V
I _D	off-state current	V _D = 400 V; T _j = 25 °C	-	-	10	μA
		$V_D = 600 \text{ V}; R_{GK(ext)} = 1 \text{ k}\Omega; T_j = 125 ^{\circ}\text{C}$	-	-	100	μA
I _R	reverse current	$V_R = 600 \text{ V}; T_j = 25 \text{ °C}; R_{GK(ext)} = 1 \text{ k}\Omega$	-	-	10	μA
		$V_R = 600 \text{ V}; T_j = 125 \text{ °C}; R_{GK(ext)} = 1 \text{ k}\Omega$	-	-	100	μA
Dynamic ch	aracteristics					
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 402 V; T_j = 125 °C; R_{GK} = 1 kΩ; (V_{DM} = 67% of V_{DRM}); exponential waveform; Fig. 13; Fig. 14	75	-	-	V/µs

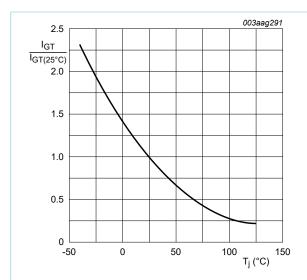


Fig. 7. Normalized gate trigger current as a function of junction temperature

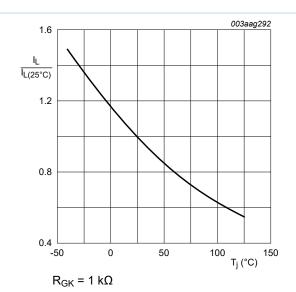


Fig. 8. Normalized latching current as a function of junction temperature

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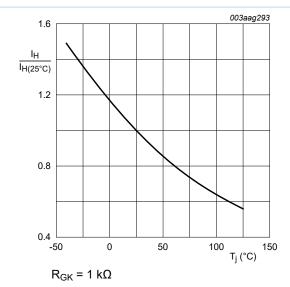


Fig. 9. Normalized holding current as a function of junction temperature

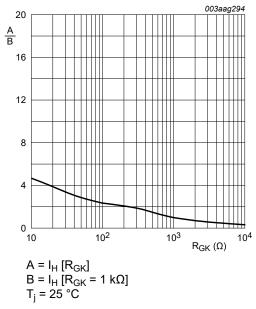
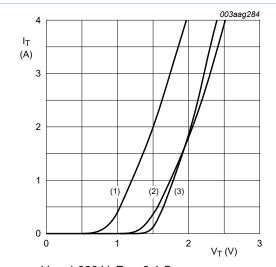


Fig. 10. Normalized holding current as a function of gate-cathode resistance (typical values)



 $V_o = 1.383 \text{ V}; R_s = 0.4 \Omega$

(1) $T_j = 125$ °C; typical values (2) $T_j = 125$ °C; maximum values (3) $T_j = 25$ °C; maximum values

Fig. 11. On-state current as a function of on-state voltage

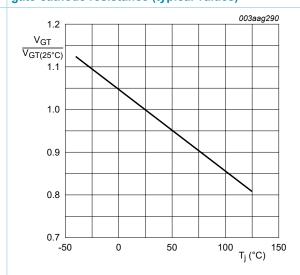


Fig. 12. Normalized gate trigger voltage as a function of junction temperature

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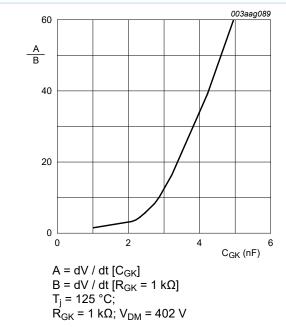


Fig. 13. Normalized dVd/dt immunity as a function of gate-cathode capacitance (typical values)

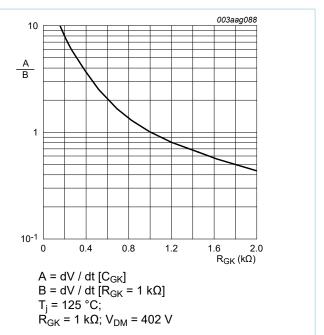
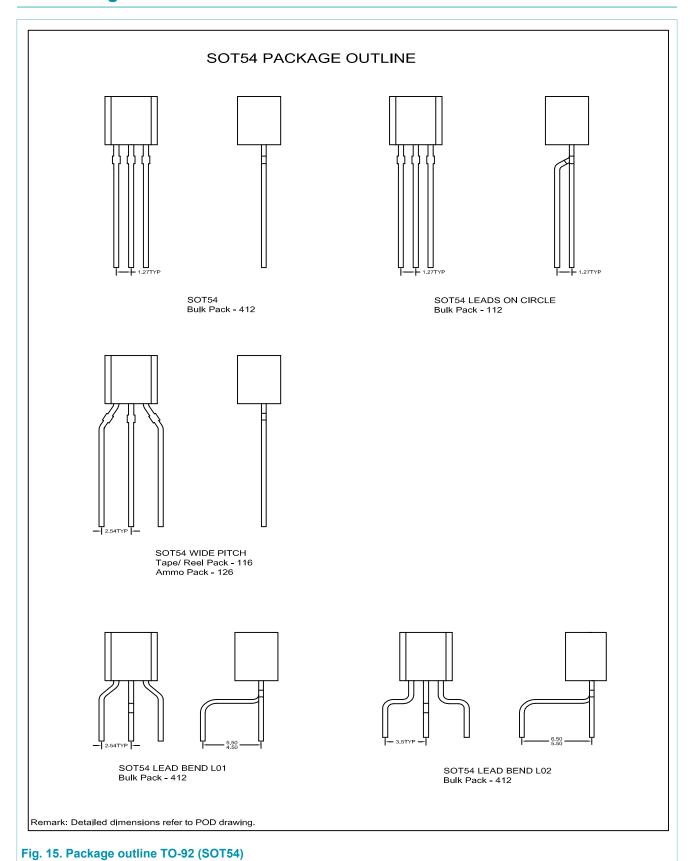


Fig. 14. Normalized dVd/dt immunity as a function of gate-cathode resistance (typical values)

10. Package outline



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11. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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